

MC74LCX257

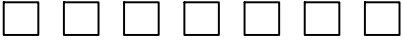


Figure 1. Pinout: 16-Lead Plastic Package
(Top View)

Figure 2. Logic Diagram

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MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Units
V_{CC}	DC Supply Voltage	-0.5 to +7.0		V
V_I	DC Input Voltage	-0.5 V_I +7.0		V
V_O	DC Output Voltage	-0.5 V_I +7.0	Output in 3-State	V
		-0.5 V_O V_{CC} + 0.5	Output in HIGH or LOW State (Note 1)	V
I_{IK}	DC Input Diode Current	-50	$V_I < GND$	mA
I_{OK}	DC Output Diode Current	-50	$V_O < GND$	mA
		+50	$V_O > V_{CC}$	mA
I_O	DC Output Source/Sink Current	50		mA
I_{CC}	DC Supply Current Per Supply Pin	100		mA
I_{GND}	DC Ground Current Per Ground Pin	100		mA
T_{STG}	Storage Temperature Range	-65 to +150		C
MSL	Moisture Sensitivity		Level 1	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- I_O absolute maximum rating must be observed.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Type	Max	Units
V_{CC}	Supply Voltage Operating	2.0	2.5, 3.3		
		1.5	2.5, 3.3		

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DC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic	Condition	T _A = -40 C to +85 C		Units
			Min	Max	
V _{IH}	HIGH Level Input Voltage (Note 2)	2.3 V V _{CC} 2.7 V	1.7		V

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DYNAMIC SWITCHING CHARACTERISTICS

Symbol	Characteristic	Condition	T _A = +25 C			Units
			Min	Typ	Max	
V _{OLP}						

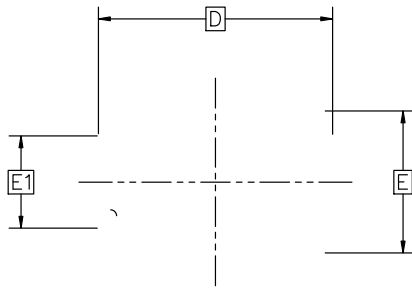


SOIC-16 9.90x3.90x1.37 1.27P
CASE 751B
ISSUE M

DATE 18 OCT 2024

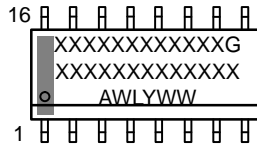
- 3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD PROTRUSION.
- 4. MAXIMUM MOLD PROTRUSION 0.17

b DIMENSION AT MAXIMUM MATE nm TOTAL IN EXCESS OF THE



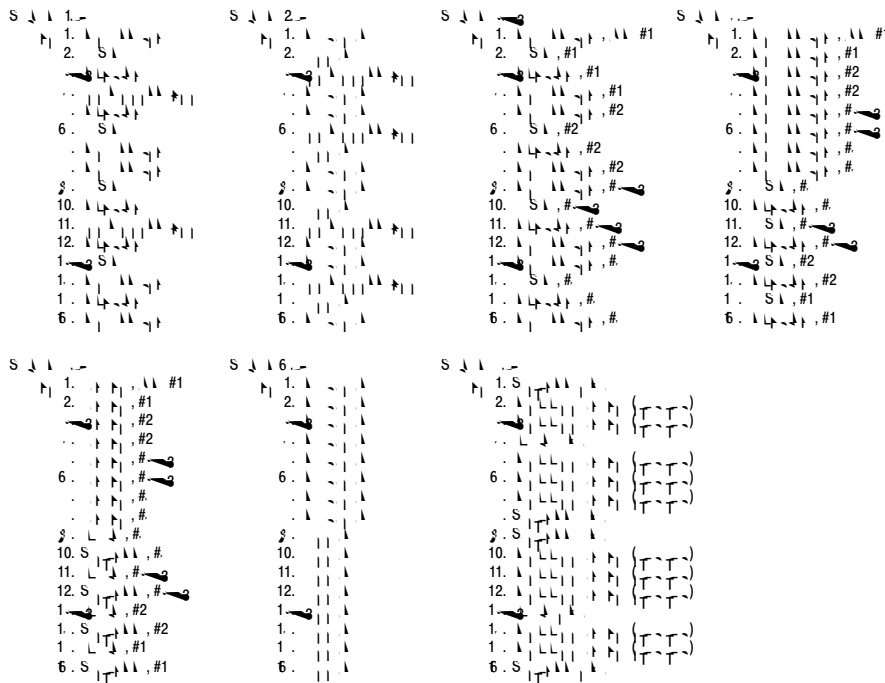
TOP VIEW

**GENERIC
MARKING DIAGRAM***



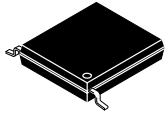
XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



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SCALE 2:1

TSSOP-16 WB
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